

ABSTRACT OF THE DISCLOSURE

An optoelectronic hermetic package comprises a frame defining a hermetic boundary and an electrical feedthrough assembly on the frame. This electrical feedthrough assembly provides electrical connections between signal wire bond areas within the hermetic boundary to electrical contact areas outside the hermetic boundary. Additionally, according to the invention, ground wire bond pad areas are also provided within the hermetic boundary, the ground wire bond pad areas being electrically connected to each other and/or the frame or other ground plane.